

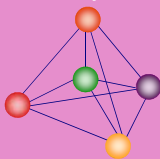
Mechanical Properties of Sn Electrodeposited in Supercritical CO₂ Emulsion Using Micro-Compression Test

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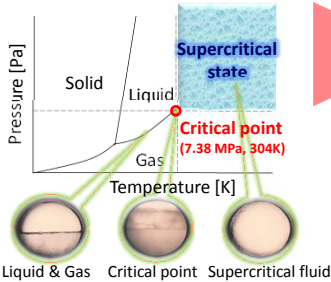
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Introduction

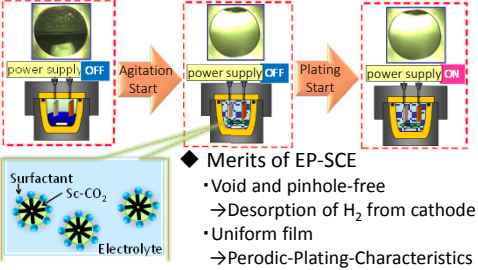
Supercritical carbon dioxide (sc-CO₂)



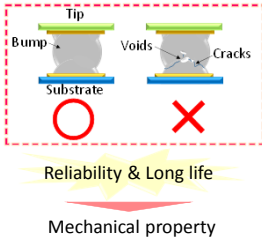
- ◆ Feature of sc-CO₂
 - low viscosity (high diffusivity)
 - low density
 - miscibility with H₂

To conduct electrochemical reactions, surfactant is added to form sc-CO₂ emulsified electrolyte

Electroplating with sc-CO₂ emulsion (EP-SCE)

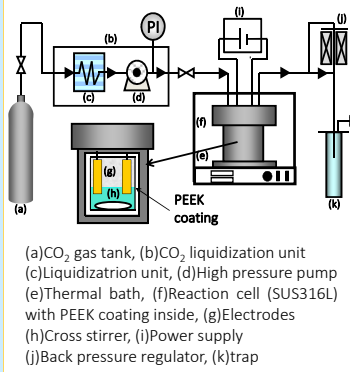


Use of Sn in load bearing component



Experimental

High pressure apparatus



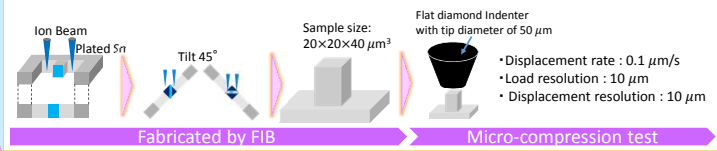
Materials

- Electrodes**
- cathode : Ni
 - anode : Sn
- Electrolyte**
- SnCl₂·2H₂O (0.22 mol/L)
 - HOC(COONH₄)(CH₂COONH₄)₂ (0.31mol/L)
 - HCl (0.015 mol/L)
 - CO₂ (20 vol.%)
- Surfactant (EP-SCE)**
- polyoxyethylene lauryl ether (C₁₂H₂₅(OCH₂CH₂)₁₅OH) 0.2 vol.% with electrolyte

Conditions

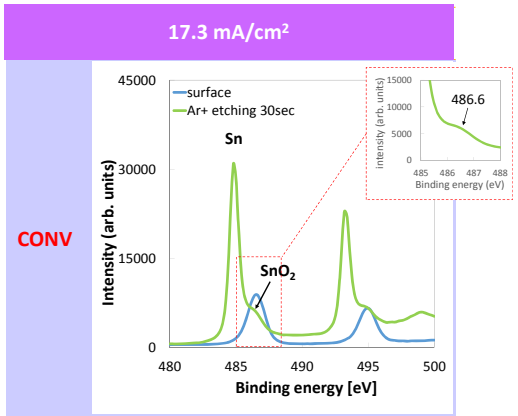
- Pressure : atmosphere (CONV) 15 MPa (EP-SCE)
 - Temperature : 343 K
 - Current density : 8.7, 17.3 mA/cm²
 - Plating time : 150, 75min (respectively)
- Theoretical film thickness , about 65 μm**

Micro-compression test



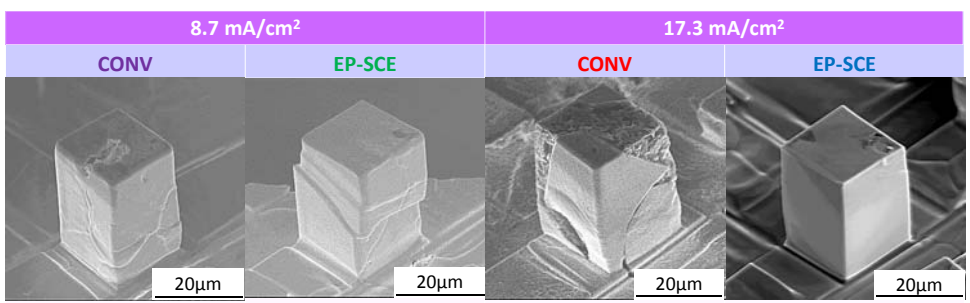
Results and discussion

Composition analyzed by XPS

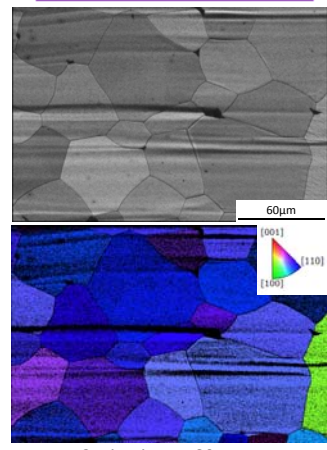


- SnO₂ is in the film by CONV.
- The film by EP-SCE consists of pure Sn.

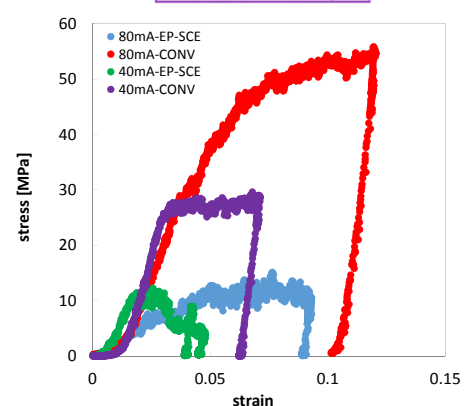
Deformed Sn pillars



Grain size of EP-SCE by EBSD



Mechanical strength



The yield strength by CONV is higher than that by EP-SCE. → SnO₂ is in the pillar by CONV.

Conclusions

- Grain size of EP-SCE is about 60 μm.
- SnO₂ is in the film by CONV.
- The yield strength by CONV is higher than that by EP-SCE.

References

- [1] T.F.M. Chang, M. Sone, Surf. Coat. Technol. 205 (2011) 3890-3899
- [2] M. Tanabe, T.F.M. Chang, H. Hosoda, T. Sato, M. Sone, ECS Electrochem. Lett., 3 (2014) D44-D45

Acknowledgment

This work has been supported by Grant-in-Aid for Scientific Research (S) (JSPS KAKENHI Grant Number 26220907)